SICK
Sensor Intelligence.

PRESS RELEASE

Less space required – more functions: SICK presents 2nd generation ultrasonic sensors

Waldkirch, November 2008 – A 25% shorter housing and additional integrated supplementary functions that can be activated via a display with expanded setting options – these are the features of the new UM30 ultrasonic sensors from SICK. The "multiplex" and "synchronisation" operating modes make the devices particularly interesting for applications in which they are used in large numbers and/or for monitoring larger areas.

The UM30 ultrasonic sensors in the cylindrical M30 housing are used for measurement and detection tasks involving objects that are optically difficult to detect, e.g. glass, foils, liquids, solar panels or wafers. Whereby the special features of the new UM30 open up new application potentials. Thanks to their shortened housings, the devices are also suitable when mounting space is limited. Various setting options can be activated directly on the sensor via the display, e.g. Multiplex Mode, which prevents mutual interference between several UM30 units. With the help of Synchronisation Mode, several UM30 units can be "connected together" to monitor larger areas. Calibration of the sensor and adjustment of a filter for measurement values are further supplementary functions offered by the new UM30-2 series. The integrated temperature compensation system ensures precise and reliable results over a long operating range. Finally the new generation of the UM30 also offers a version that has both an analogue and a PNP switching output.